1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD128 small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 2$ A
- Reverse voltage: $V_R \leq 30$ V
- Low forward voltage
- High power capability due to clip-bond technology
- AEC-Q101 qualified
- Small and flat lead SMD plastic package
- Capable for reflow and wave soldering

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications

4. Quick reference data

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$I_{F(AV)}$</td>
<td>average forward current</td>
<td>$\delta = 0.5$ ; $f = 20$ kHz; $T_{amb} \leq 100$ °C; square wave</td>
<td>-</td>
<td>-</td>
<td>2 A</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>$\delta = 0.5$ ; $f = 20$ kHz; $T_{sp} \leq 140$ °C; square wave</td>
<td>-</td>
<td>-</td>
<td>2 A</td>
<td></td>
</tr>
<tr>
<td>$V_R$</td>
<td>reverse voltage</td>
<td>$T_j = 25$ °C</td>
<td>-</td>
<td>-</td>
<td>30  V</td>
<td></td>
</tr>
<tr>
<td>$V_F$</td>
<td>forward voltage</td>
<td>$I_F = 2$ A; $T_j = 25$ °C</td>
<td>-</td>
<td>400</td>
<td>450 mV</td>
<td></td>
</tr>
<tr>
<td>$I_R$</td>
<td>reverse current</td>
<td>$V_R = 30$ V; $T_j = 25$ °C</td>
<td>35</td>
<td>100</td>
<td>µA</td>
<td></td>
</tr>
</tbody>
</table>

[1] Device mounted on a ceramic PCB, $\text{Al}_2\text{O}_3$, standard footprint.
5. Pinning information

Table 2. Pinning information

<table>
<thead>
<tr>
<th>Pin</th>
<th>Symbol</th>
<th>Description</th>
<th>Simplified outline</th>
<th>Graphic symbol</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>K</td>
<td>cathode[1]</td>
<td></td>
<td>K</td>
</tr>
<tr>
<td>2</td>
<td>A</td>
<td>anode</td>
<td></td>
<td>A</td>
</tr>
</tbody>
</table>

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

<table>
<thead>
<tr>
<th>Type number</th>
<th>Package</th>
<th>Description</th>
<th>Version</th>
</tr>
</thead>
<tbody>
<tr>
<td>PMEG3020BEP</td>
<td>CFP5</td>
<td>plastic, surface mounted package; 2 terminals; 4 mm pitch; 3.8 mm x 2.6 mm x 1 mm body</td>
<td>SOD128</td>
</tr>
</tbody>
</table>

7. Marking

Table 4. Marking codes

<table>
<thead>
<tr>
<th>Type number</th>
<th>Marking code</th>
</tr>
</thead>
<tbody>
<tr>
<td>PMEG3020BEP</td>
<td>A4</td>
</tr>
</tbody>
</table>
8. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>V_R</td>
<td>reverse voltage</td>
<td>T_j = 25 °C</td>
<td>-</td>
<td>30</td>
<td>V</td>
</tr>
<tr>
<td>I_{F(AV)}</td>
<td>average forward current</td>
<td>δ = 0.5 ; f = 20 kHz; T_amb ≤ 100 °C; square wave</td>
<td>[1]</td>
<td>2</td>
<td>A</td>
</tr>
<tr>
<td></td>
<td></td>
<td>T_j = 25 °C</td>
<td>-</td>
<td>2</td>
<td>A</td>
</tr>
<tr>
<td>I_{FSM}</td>
<td>non-repetitive peak</td>
<td>t_p = 8 ms; square wave; T_j(init) = 25 °C</td>
<td>-</td>
<td>50</td>
<td>A</td>
</tr>
<tr>
<td>P_{tot}</td>
<td>total power dissipation</td>
<td>T_amb ≤ 25 °C</td>
<td>[2]</td>
<td>625</td>
<td>mW</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[3]</td>
<td>1.05</td>
<td>W</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[1]</td>
<td>2.1</td>
<td>W</td>
</tr>
<tr>
<td>T_j</td>
<td>junction temperature</td>
<td></td>
<td>-</td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>T_amb</td>
<td>ambient temperature</td>
<td></td>
<td>-55</td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>T_stg</td>
<td>storage temperature</td>
<td></td>
<td>-65</td>
<td>150</td>
<td>°C</td>
</tr>
</tbody>
</table>


9. Thermal characteristics

Table 6. Thermal characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>R_{θ(j-a)}</td>
<td>thermal resistance</td>
<td>in free air</td>
<td>[1]</td>
<td>-</td>
<td>200</td>
<td>KW</td>
</tr>
<tr>
<td></td>
<td>from junction to ambient</td>
<td></td>
<td>[3]</td>
<td>-</td>
<td>120</td>
<td>KW</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[4]</td>
<td>-</td>
<td>60</td>
<td>KW</td>
</tr>
<tr>
<td>R_{θ(j-sp)}</td>
<td>thermal resistance</td>
<td></td>
<td>[5]</td>
<td>-</td>
<td>12</td>
<td>KW</td>
</tr>
<tr>
<td></td>
<td>from junction to solder</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>point</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

[2] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values
10. Characteristics

Table 7. Characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_F$</td>
<td>forward voltage</td>
<td>$I_F = 0.1 \text{ A}; T_J = 25 \degree \text{C}$</td>
<td>-</td>
<td>290</td>
<td>340</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 0.5 \text{ A}; T_J = 25 \degree \text{C}$</td>
<td>-</td>
<td>340</td>
<td>400</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 1 \text{ A}; T_J = 25 \degree \text{C}$</td>
<td>-</td>
<td>365</td>
<td>420</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 1.5 \text{ A}; T_J = 25 \degree \text{C}$</td>
<td>-</td>
<td>385</td>
<td>440</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$I_F = 2 \text{ A}; T_J = 25 \degree \text{C}$</td>
<td>-</td>
<td>400</td>
<td>450</td>
<td>mV</td>
</tr>
<tr>
<td>$I_R$</td>
<td>reverse current</td>
<td>$V_R = 5 \text{ V}; T_J = 25 \degree \text{C}$</td>
<td>-</td>
<td>4</td>
<td>-</td>
<td>µA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 10 \text{ V}; T_J = 25 \degree \text{C}$</td>
<td>-</td>
<td>6</td>
<td>-</td>
<td>µA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 30 \text{ V}; T_J = 25 \degree \text{C}$</td>
<td>-</td>
<td>35</td>
<td>100</td>
<td>µA</td>
</tr>
<tr>
<td>$C_d$</td>
<td>diode capacitance</td>
<td>$V_R = 1 \text{ V}; f = 1 \text{ MHz}; T_J = 25 \degree \text{C}$</td>
<td>-</td>
<td>340</td>
<td>-</td>
<td>pF</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_J = 25 \degree \text{C}$</td>
<td>-</td>
<td>120</td>
<td>-</td>
<td>pF</td>
</tr>
</tbody>
</table>

Ceramic PCB, Al$_2$O$_3$, standard footprint

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values
Fig. 4. Forward current as a function of forward voltage; typical values

- (1) $T_J = 150°C$
- (2) $T_J = 125°C$
- (3) $T_J = 85°C$
- (4) $T_J = 25°C$
- (5) $T_J = -40°C$

Fig. 5. Reverse current as a function of reverse voltage; typical values

- (1) $T_J = 125°C$
- (2) $T_J = 85°C$
- (3) $T_J = 25°C$
- (4) $T_J = -40°C$

Fig. 6. Diode capacitance as a function of reverse voltage; typical values

- $f = 1\, \text{MHz}$; $T_{\text{amb}} = 25\, °C$

Fig. 7. Average forward power dissipation as a function of average forward current; typical values

- $T_J = 150\, °C$
- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$
2 A low VF MEGA Schottky barrier rectifier

Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values

\[ P_{\text{R(\text{AV})}} \] (W)

\[ V_{R} \] (V)

\[ T_{j} = 125 \, ^{\circ}\text{C} \]

1. \( \delta = 1 \)
2. \( \delta = 0.9 \)
3. \( \delta = 0.8 \)
4. \( \delta = 0.5 \)

FR4 PCB, standard footprint

Fig. 9. Average forward current as a function of ambient temperature; typical values

\[ I_{F(\text{AV})} \] (A)

\[ T_{\text{amb}} \] (°C)

FR4 PCB, mounting pad for cathode 1 cm²

\[ T_{j} = 150 \, ^{\circ}\text{C} \]

1. \( \delta = 1; \text{DC} \)
2. \( \delta = 0.5; f = 20 \text{ kHz} \)
3. \( \delta = 0.2; f = 20 \text{ kHz} \)
4. \( \delta = 0.1; f = 20 \text{ kHz} \)

Ceramic PCB, Al₂O₃, standard footprint

\[ T_{j} = 150 \, ^{\circ}\text{C} \]

1. \( \delta = 1; \text{DC} \)
2. \( \delta = 0.5; f = 20 \text{ kHz} \)
3. \( \delta = 0.2; f = 20 \text{ kHz} \)
4. \( \delta = 0.1; f = 20 \text{ kHz} \)

Fig. 10. Average forward current as a function of ambient temperature; typical values

Fig. 11. Average forward current as a function of ambient temperature; typical values
Fig. 12. Average forward current as a function of solder point temperature; typical values

11. Test information

The current ratings for the typical waveforms are calculated according to the equations:

\[ I_{F(AV)} = I_m \times \delta \]

with \( I_m \) defined as peak current, \( I_{RMS} = I_{F(AV)} \) at DC, and \( I_{RMS} = I_m \times \sqrt{\delta} \) with \( I_{RMS} \) defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.
12. Package outline

![Diagram of package outline CFP5 (SOD128)](image)

Fig. 14. Package outline CFP5 (SOD128)

13. Soldering

![Diagram of reflow soldering footprint for CFP5 (SOD128)](image)

Fig. 15. Reflow soldering footprint for CFP5 (SOD128)
Fig. 16. Wave soldering footprint for CFP5 (SOD128)
## 14. Revision history

<table>
<thead>
<tr>
<th>Data sheet ID</th>
<th>Release date</th>
<th>Data sheet status</th>
<th>Change notice</th>
<th>Supersedes</th>
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</table>

**Modifications:**
- Features and benefits: Capable for reflow and wave soldering added
- Soldering: Wave soldering footprint added

<table>
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<tr>
<th>Data sheet ID</th>
<th>Release date</th>
<th>Data sheet status</th>
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<td>20091016</td>
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<td>-</td>
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15. Legal information

Data sheet status

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<tbody>
<tr>
<td>Objective [short] data sheet</td>
<td>Development</td>
<td>This document contains data from the objective specification for product development.</td>
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<tr>
<td>Preliminary [short] data sheet</td>
<td>Qualification</td>
<td>This document contains data from the preliminary specification.</td>
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<tr>
<td>Product [short] data sheet</td>
<td>Production</td>
<td>This document contains the product specification.</td>
</tr>
</tbody>
</table>

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nexperia.com.

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